


Standardized Information for Process/Product Change Notification (PCN)

Form provided by ZVEI - Revision 3.0.0

1. PCN basic data		
1.1 Company		TAIWAN SEMICONDUCTOR CO., LTD.
1.2 PCN No.	PCN20001	
1.3 Title of PCN	New Subcon Qualification for affected SSD Part Numbers	
1.4 Product Category	Active Components - Discrete Components	
1.5 Issue date	2020/01/09	
1.6 PCN revision history (optional)	1.7 Issue date of previous revision (optional)	1.8 Delta to previous revision (optional)

2. PCN Team		
2.1 Contact supplier		
2.1.1 Name	Sunnie Lin	
2.1.2 Phone	+886 2 8913 1588 Ext.2205	
2.1.3 Email	sunnie@mail.ts.com.tw	
2.2 Team supplier (optional)		
2.2.1 Name (optional)	2.2.2 Phone (optional)	2.2.3 Email (optional)
Chris Lin	+886 2 89131588 Ext.2406	chris_lin@mail.ts.com.tw
Rolly Natividad	+886 2 89131588 Ext.2209	roly.natividad@mail.ts.com.tw

3. Changes			
No.	3.0 Ident	3.1 Category	3.2 Type of change
#1	SEM-PA-18	PROCESS - ASSEMBLY	Move of all or part of assembly to a different location/site/subcontractor.
#2			
#3			
#4			
#5			

4. Description of change		
	Old	New
Change #1	Current Subcon : Subcon A for : 1. SOT-23 (SKY, SWCH & TRA) 2. SOT-323 (SKY, SWCH & TRA) Subcon B for: 1. SOT-23 (SKY, SWCH & ZENER) 2. SOD-323 (SKY & SWCH) Subcon C for: 1. SOD-323 (SKY & SWCH) Note: Subcon A, B & C will continue mass production support.	Additional Subcon : Subcon D for: 1. SOT-23 (SKY, SWCH, TRA & ZENER) 2. SOT-323 (SKY, SWCH & TRA) 3. SOD-323 (SKY & SWCH)
Change #2		
Change #3		
Change #4		
Change #5		
4.6 Anticipated impact on form, fit, function, reliability or processability?	This change has no impact on any of the electrical parameters of the products involve. The product test conditions, test limits and performance will remain unchanged. Subcon "D" facility will produce products with the same level of quality and reliability as the existing subcon sites. In addition there is no changes in POD (Package Outline Dimensions).	

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4.7 Reference parts with customer number (optional)	
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5. Reason / motivation for change

5.1 Motivation	Subcon D is capable to support assembly of SOT-23, SOT-323 and SOD-323 packages with the level of quality and reliability comparable to the existing subcon sites.
5.2 Additional explanation (optional)	<p>Taiwan Semiconductor Co., LTD (TSC) qualified Subcon "D" as an alternate assembly and test location for SOT-23, SOT-323 and SOD-323 package types.</p> <p>The additional flexibility resulting from the qualification of Subcon "D" will give TSC improved ability to respond to high volumes orders with minimum lead time.</p> <p>TSC will continue to assemble and test SOT-23, SOT-323 and SOD-323 products using the existing qualified subcon sites.</p>

6. Marking of parts / traceability of change

6.1 Description	Use factory code to traceability
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7. Timing / schedule

7.1 Date of qualification results	2019/11/30	
7.2 Last order date (optional)		N/A
7.3 Last delivery date (optional)		N/A
7.4 Intended start of delivery	2020/07/07	
7.5 Qualification samples available?	When get customer order and after 2 weeks can be submitted	
7.6 Customer feedback required until	2020/02/24	

8. Qualification / validation

8.1 Description (e.g. qual. plan/report, AEC-Q...)	Qualification/validation is in accordance with applicable JESD22 and TSC qualification plan requirements.		
8.2 Qualification report and qualification results	available (see attachment)	issue date	2019/11/30

9. Input to customer for risk assessment process

Human Resource : No Risk
 Equipment : No Risk
 Technique-Wafer : No Risk
 Technique-Assembly : No Risk
 Form/ Fit / Function : No Risk
 Reliability : No Risk

10. Attachments (e.g. new datasheet, additional documentation, pictures, process flow, sample plan, ...)

Refer to the official e-mail announcement for the applicable documents.

11. Affected parts

11.1 Current					11.2 New (if applicable)				
11.1.1 Customer Part No.	11.1.2 Supplier Part Name	11.1.3 Supplier Part No. (optional)	11.1.4 Package Name	11.1.5 Part Description (optional)	11.1.6 Additional Part Information	11.2.2 Supplier Part Name	11.2.3 Supplier Part No. (optional)	11.2.4 Package Name	11.2.6 Additional Part Information (optional)

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